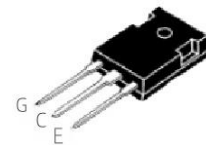
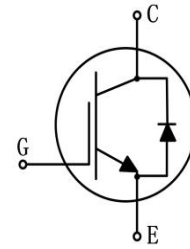


### MAIN CHARACTERISTICS

$I_C$ @TC=100°C	40A
$V_{CE}$	1200V
VCE(sat)-typ	1.9V



TO-247

### FEATURES

- Trench and field-stop technology
- High speed switching
- Low collector to emitter saturation voltage
- Easy parallel switching capability
- Short circuit withstands time 10 $\mu$ s
- High ruggedness performance

### APPLICATIONS

- Inverter
- Motor driver

### MECHANICAL DATA

- Case: Molded plastic
- Mounting Position: Any
- Molded Plastic: UL Flammability Classification Rating 94V-0
- Lead free in compliance with EU RoHS 2011/65/EU directive
- Solder bath temperature 275°C maximum, 10s per JESD 22-B106

### Product specification classification

Part Number	Package	Mode Name	Pack
LGT40N120HB	TO-247	LGT40N120HB	Tube

### Maximum Ratings

Characteristics	Symbol	Value	Unit
		247	
Collector-emitter voltage	$V_{CES}$	1200	V
Gate-emitter voltage	$V_{GES}$	$\pm 20$	V
Continuous collector current (TC=25°C)	$I_C$	80	A
Continuous collector current (TC=100°C)		40	A
Pulsed collector current, tp limited by Tvjmax	$I_{CM}$	160	A
Diode continuous forward current (TC=100°C)	$I_F$	40	A
Diode maximum current, tp limited by Tvjmax	$I_{FM}$	160	A
Power dissipation (TC=25°C)	$P_{tot}$	625	W
Operating junction temperature range	$T_{vj}$	-40 to +175	°C
Storage temperature range	$T_{stg}$	-55 to +150	°C

### Thermal characteristics

Characteristics	Symbol	Values		Unit
		Typ	Max.	
Thermal resistance, junction to case for IGBT	$R_{th(j-c)}$	-	0.35	K/W
Thermal resistance, junction to case for Diode	$R_{th(j-c)}$	-	0.70	K/W
Thermal resistance, junction to ambient	$R_{th(j-a)}$	-	40	K/W

Note1: Pulse test: 300  $\mu$ s pulse width, 2 % duty cycle

### Electrical characteristics of IGBT at $T_{vj}=25^\circ\text{C}$ unless otherwise specified

#### Static characteristics

Characteristics	Test Condition	Symbol	Min	Typ	Max	Unit
Collector-emitter breakdown voltage	$V_{GE}=0V, I_C=250\mu A$	$BV_{CES}$	1200	-	-	V
Collector-emitter leakage current	$V_{CE}=1200V, V_{GE}=0V$	$I_{CES}$	-	-	100	$\mu A$
Gate leakage current, forward	$V_{GE}=\pm 20V, V_{CE}=0V$	$I_{GES}$	-	-	$\pm 100$	nA
Gate-emitter threshold voltage	$V_{GE}=V_{CE}, I_C=1mA$	$V_{GE(th)}$	5	6	7	V
Collector-emitter saturation voltage	$V_{GE}=15V, I_C=40A$	$V_{CE(sat)}$	-	1.9	-	V
	$V_{GE}=15V, I_C=40A, T_{vj}=175^\circ\text{C}$		-	2.3	-	V

#### Dynamic characteristics

Characteristics	Test Condition	Symbol	Min	Typ	Max	Unit
Input capacitance	$V_{CE}=30V$	$C_{ies}$	-	9780	-	pF
Output capacitance	$V_{GE}=0V$	$C_{oes}$	-	140	-	pF
Reverse transfer capacitance	$f=1MHz$	$C_{res}$	-	42	-	pF
Total gate charge	$V_{CC}=960V, V_{GE}=15V, I_C=40A$	$Q_g$	-	269	-	nC

### Electrical characteristics of IGBT at $T_{vj}=25^{\circ}\text{C}$ unless otherwise specified

#### Switching characteristics

Characteristics	Test Condition	Symbol	Min	Typ	Max	Unit
Turn-on delay time	$V_{CC}=600\text{V}$ $V_{GE}=15\text{V}$ $I_C=40\text{A}$ $R_G=10\Omega$ Inductive load	td(on)	-	80	-	ns
Rise time		tr	-	77	-	ns
Turn-off delay time		td(off)	-	308	-	ns
Fall time		tf	-	67	-	ns
Turn-on energy		Eon	-	2.1	-	mJ
Turn-off energy		Eoff	-	1.4	-	mJ
Total switching energy		Ets	-	3.5	-	mJ
Turn-on delay time	$V_{CC}=600\text{V}$ $V_{GE}=15\text{V}$ $I_C=40\text{A}$ $R_G=10\Omega$ Inductive load $T_{vj}=175^{\circ}\text{C}$	td(on)	-	70	-	ns
Rise time		tr	-	75	-	ns
Turn-off delay time		td(off)	-	352	-	ns
Fall time		tf	-	132	-	ns
Turn-on energy		Eon	-	2.5	-	mJ
Turn-off energy		Eoff	-	2.4	-	mJ
Total switching energy		Ets	-	4.9	-	mJ

### Electrical characteristics of Diode at $T_{vj}=25^{\circ}\text{C}$ unless otherwise specified

Characteristics	Test Condition	Symbol	Min	Typ	Max	Unit
Diode forward voltage	$I_F=40\text{A}$	VF	-	3.1	-	V
	$I_F=40\text{A}$ $T_{vj}=175^{\circ}\text{C}$		-	2.3	-	V
Diode reverse recovery time	$V_R=600\text{V}$	trr	-	170	-	ns
Diode peak reverse recovery current	$I_F=40\text{A}$	Irrm	-	17	-	A
Diode reverse recovery charge	$diF/dt=-750\text{A}/\mu\text{s}$	Qrr	-	1100	-	nC
Diode reverse recovery time	$V_R=600\text{V}$	trr	-	285	-	ns
Diode peak reverse recovery current	$I_F=40\text{A}$	Irrm	-	28	-	A
Diode reverse recovery charge	$diF/dt=-750\text{A}/\mu\text{s}$ $T_{vj}=175^{\circ}\text{C}$	Qrr	-	3300	-	nC

### RATINGS AND CHARACTERISTIC CURVES

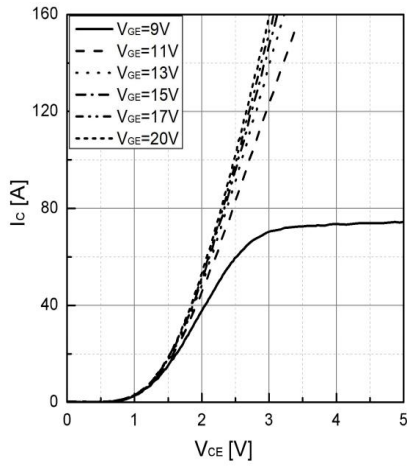


Fig 1. Typical output characteristic ( $T_{vj}=25^{\circ}\text{C}$ )

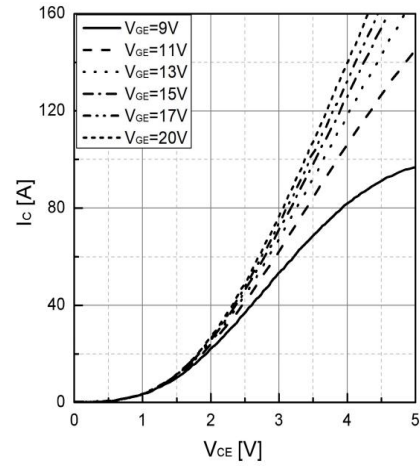


Fig 2. Typical output characteristic ( $T_{vj}=175^{\circ}\text{C}$ )

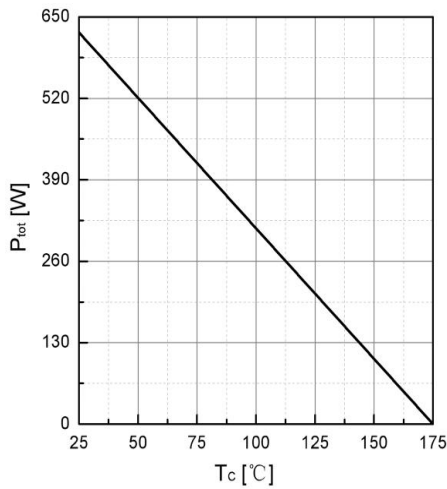


Fig 3. Power dissipation as a function of  $T_c$

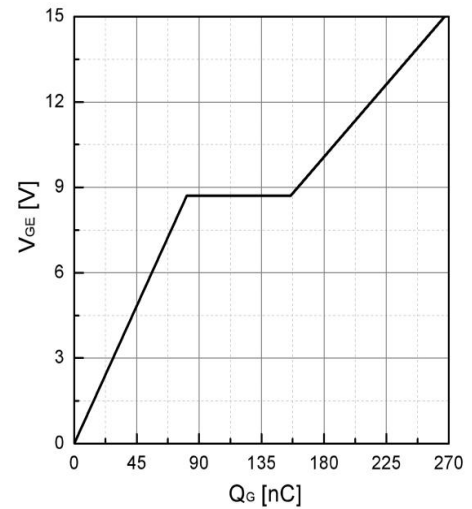


Fig 4. Typical Gate charge

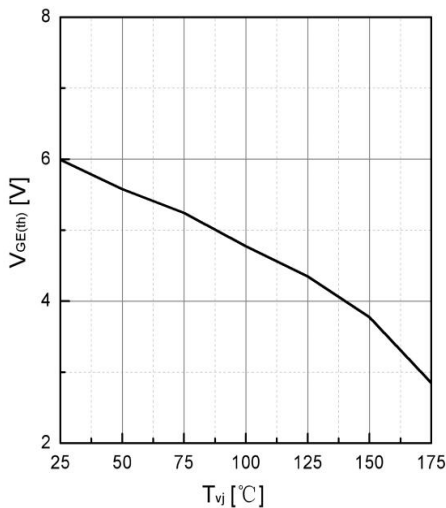


Fig 5. Typical  $V_{GE(th)}$  as a function of  $T_{vj}$   
( $I_c=1\text{mA}$ )

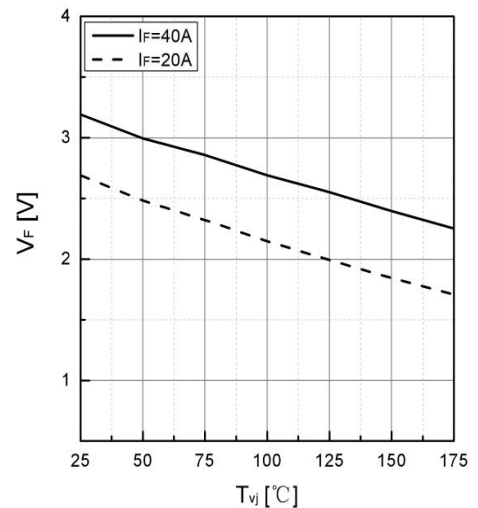


Fig 6. Typical  $V_F$  as a function of  $T_{vj}$

### RATINGS AND CHARACTERISTIC CURVES

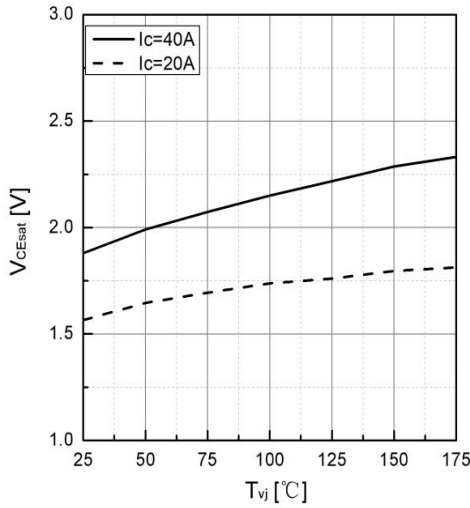


Fig 7. Typical  $V_{CEsat}$  as a function of  $T_{vj}$

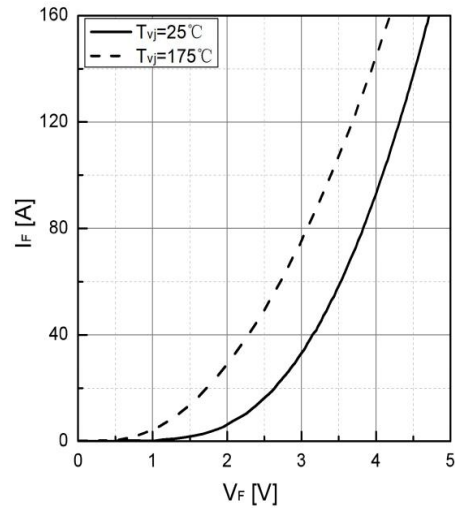


Fig 8. Typical  $I_F$  as a function of  $V_F$

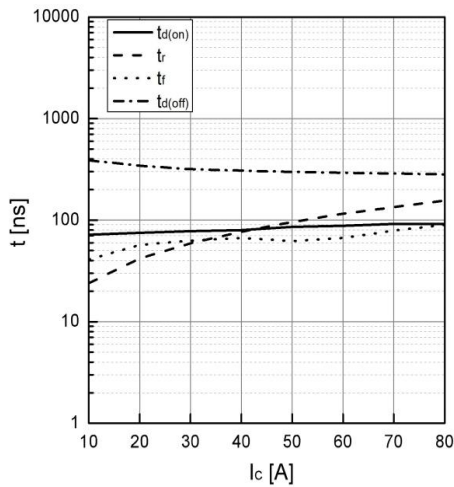


Fig 9. Typical switching time as a function of  $I_c$

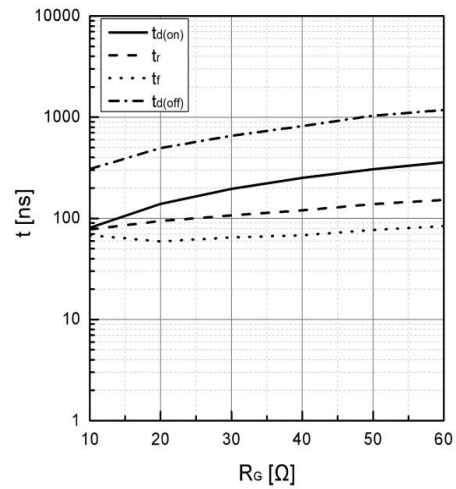


Fig 10. Typical switching times as a function of  $R_G$

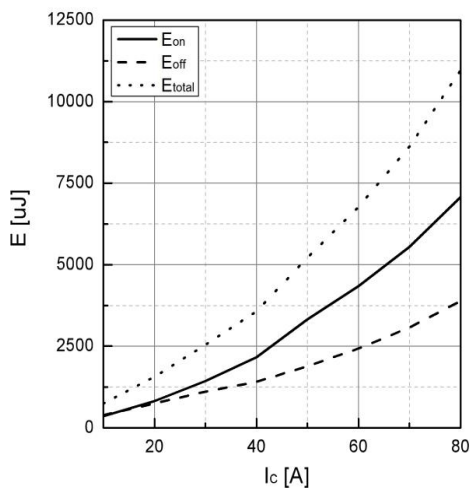


Fig 11. Typical switching energy losses as a function of  $I_c$

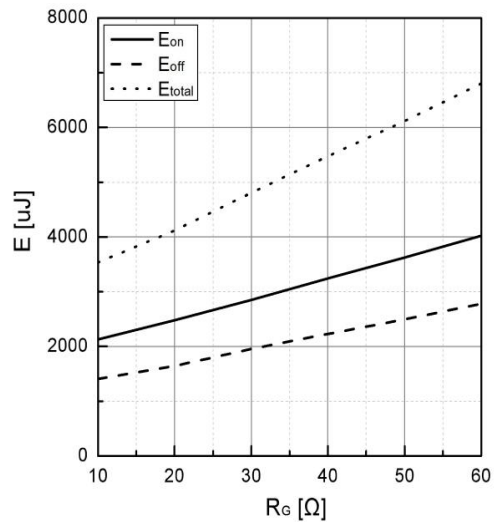


Fig 12. Typical switching energy losses as a function of  $R_G$

### RATINGS AND CHARACTERISTIC CURVES

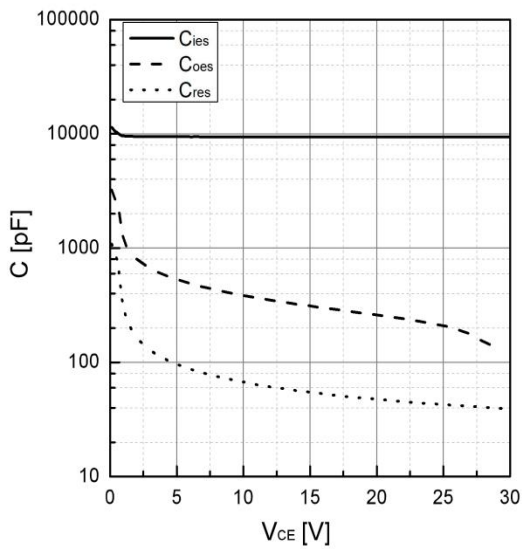


Fig 13. Typical capacitance as a function of  $V_{CE}$   
( $f=1\text{MHz}$ ,  $V_{GE}=0\text{V}$ )

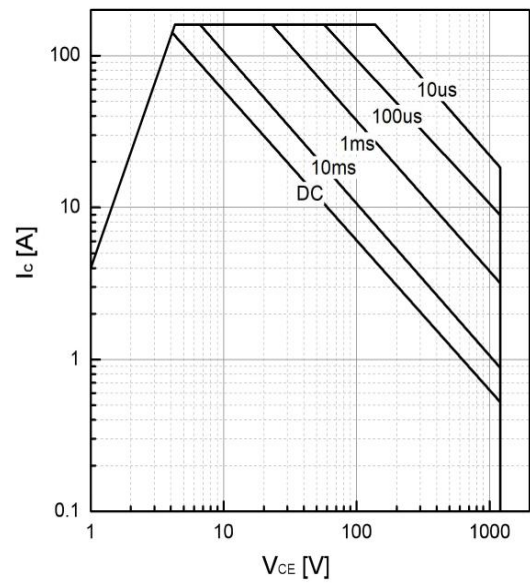


Fig 14. Safe operating area

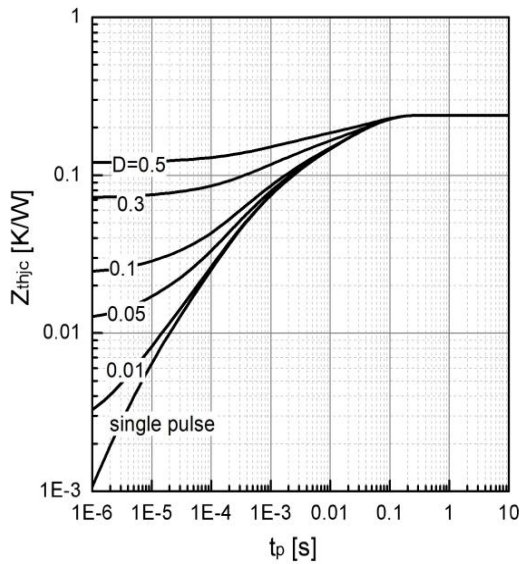
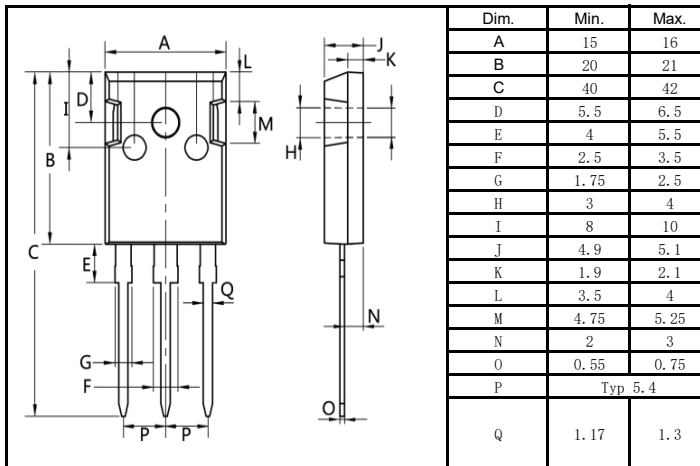


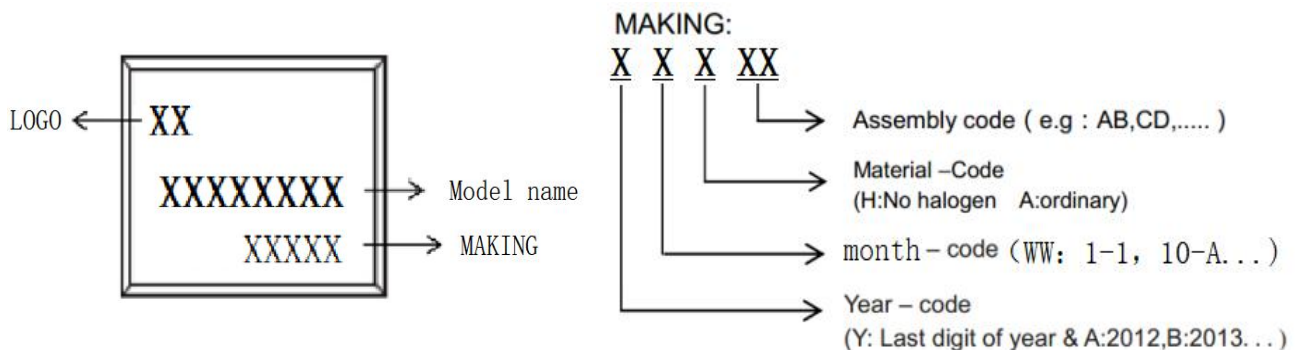
Fig 15. Transient thermal impedance of IGBT

### Package Outline Dimensions millimeters

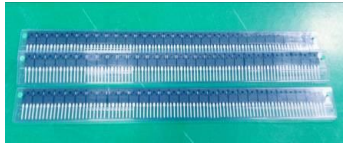


T0-247



### Marking on the body



### packing instruction

PKG	最小包装	内盒	外箱
TO-247			
	30PCS/管	600pcs/盒	3000pcs/箱

### Notice

All product, product specifications and data are subject to change without notice to improve. The right to explain is owned by LINGXUN electronics company.

Confirm that operation temperature is within the specified range described in the product specification. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.

LINGXUN electronics shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.